


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	WAFER GRINDING APPARATUS		
Application Type : regular, utility Attorney Docket Number : LKSP0034USA			
Correspondence address: Customer Number: 027765			
			
Inventors Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Given Name: Mu-Jung Family Name: Wu Residence: City of Residence: Hsin-Chu City Country of Residence: TW Address-1 of Mailing Address: No. 3, Alley 51, Lane 400, Ming-Hu Rd. Address-2 of Mailing Address: City of Mailing Address: Hsin-Chu City State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address: TW Phone: Fax: E-mail: <u>Inventor 2:</u> Applicant Authority Type: Inventor Citizenship: TW Given Name: Ming-Yen Family Name: Chung Residence: City of Residence: Kao-Hsiung City			

Country of Residence: TW
Address-1 of Mailing Address: No. 2, Lane 370, Chin-Ding Rd., San-Min District
Address-2 of Mailing Address:
City of Mailing Address: Kao-Hsiung City
State of Mailing Address:
Postal Code of Mailing Address:
Country of Mailing Address: TW
Phone:
Fax:
E-mail:

Attorney Information:

practitioner(s) at Customer Number:

027765



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.